

Surface Mount PTC

0ZCD Series

2920 Chip
RoHS6 Compliant

0ZCD1006D



Application

All high-density boards

Product Features

2920 Chip Size, Fast Trip Time, High Hold Currents

Operating (Hold Current) Range

300mA ~ 2.5A

Maximum Voltage

16 ~ 60V (per table)

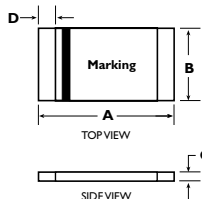
Temperature Range

-40°C to 85°C

Agency Approval

UL Component (E305051)

Product Dimensions



Part Number	A		B		C		D
	Min	Max	Min	Max	Min	Max	Min
0ZCD0030	6.73	7.98	4.8	5.44	0.6	1.15	0.35
0ZCD0050	6.73	7.98	4.8	5.44	0.6	1.15	0.35
0ZCD0075	6.73	7.98	4.8	5.44	0.6	1.15	0.35
0ZCD0110	6.73	7.98	4.8	5.44	0.4	1.0	0.35
0ZCD0125	6.73	7.98	4.8	5.44	0.4	0.9	0.35
0ZCD0150	6.73	7.98	4.8	5.44	0.4	0.9	0.35
0ZCD0185	6.73	7.98	4.8	5.44	0.3	0.9	0.35
0ZCD0200	6.73	7.98	4.8	5.44	0.3	0.9	0.35
0ZCD0250	6.73	7.98	4.8	5.44	0.3	0.9	0.35

Standard Package

2,000 fuses in 7 inches dia. reel, 8mm wide tape, 4mm pitch, per EIA-481 (equivalent IEC-286 part 3). P/N code - 2C.

PTC Marking

"bel" or "b", IH code.

Electrical Characteristics (23 °C)

Part Number	Hold Current I _H , A	Trip Current I _T , A	Max Time to Trip		Max Current I _{max} , A	Rated Voltage V _{max} , V _{dc}	Typical Power P _d , W	Resistance Tolerance		
			Current, A	Seconds				R _{min} Ohms	R _{max} Ohms	R _{1max} Ohms
A	0.30	0.6	1.5	3.0	10	60	1.5	1.000	2.000	4.800
B	0.50	1.0	2.5	4.0	10	60	1.5	0.300	0.700	1.400
C	0.75	1.5	8.0	0.3	40	33	1.5	0.180	0.310	1.000
D	1.10	2.2	8.0	0.5	40	33	1.5	0.090	0.170	0.410
E	1.25	2.5	8.0	2.0	40	33	1.5	0.050	0.131	0.250
F	1.50	3.0	8.0	2.0	40	33	1.5	0.050	0.108	0.230
G	1.85	3.7	8.0	2.5	40	33	1.5	0.040	0.076	0.150
H	2.00	4.0	8.0	4.5	40	16	1.5	0.035	0.065	0.120
I	2.50	5.0	8.0	16.0	40	16	1.5	0.025	0.041	0.085

- I_H** Hold current-maximum current at which the device will not trip in still air at 23°C.
- I_T** Trip current-minimum current at which the device will always trip in still air at 23°C.
- I_{max}** Maximum fault current device can withstand without damage at rated voltage (V_{max}).
- V_{max}** Maximum voltage device can withstand without damage at its rated current.
- P_d** Typical power dissipated from device when in the tripped state in 23°C still air environment.
- R_{min}** Minimum device resistance at 23°C.
- R_{max}** Maximum device resistance at 23°C.
- R_{1max}** Maximum device resistance at 23°C, 1 hour after initial device trip.

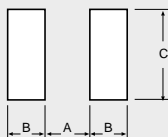
Termination pad characteristics

Termination pad materials

Tin-plated copper

Pad Layout, Solder Reflow and Rework Recommendations

The dimensions in the table below provide the recommended pad layout for each 0ZCD device

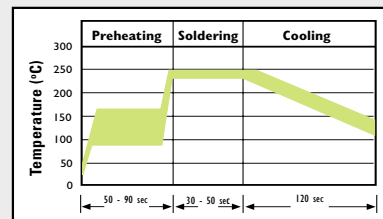


A Nominal		B Nominal		C Nominal	
mm	inch	mm	inch	mm	inch
5.10	0.2008	2.30	0.0906	5.60	0.2205

Solder Reflow

* Due to "lead free/RoHS6" construction of these PTC devices, the required Temperature and Dwell Time in the "Soldering" zone of the reflow profile are greater than those used for non-RoHS devices.

1. Recommended reflow methods; IR, vapor phase oven, hot air oven.
2. The 0ZCD Series is suitable for wave solder application methods.
3. Recommended maximum paste thickness is 0.25mm.
4. Devices are compatible with standard industry cleaning solvents and methods.



Caution

If reflow temperature/dwell times exceed the recommended Profile, the electrical performance of the PTC may be affected.

Rework

Use standard industry practices.

Specifications subject to change without notice

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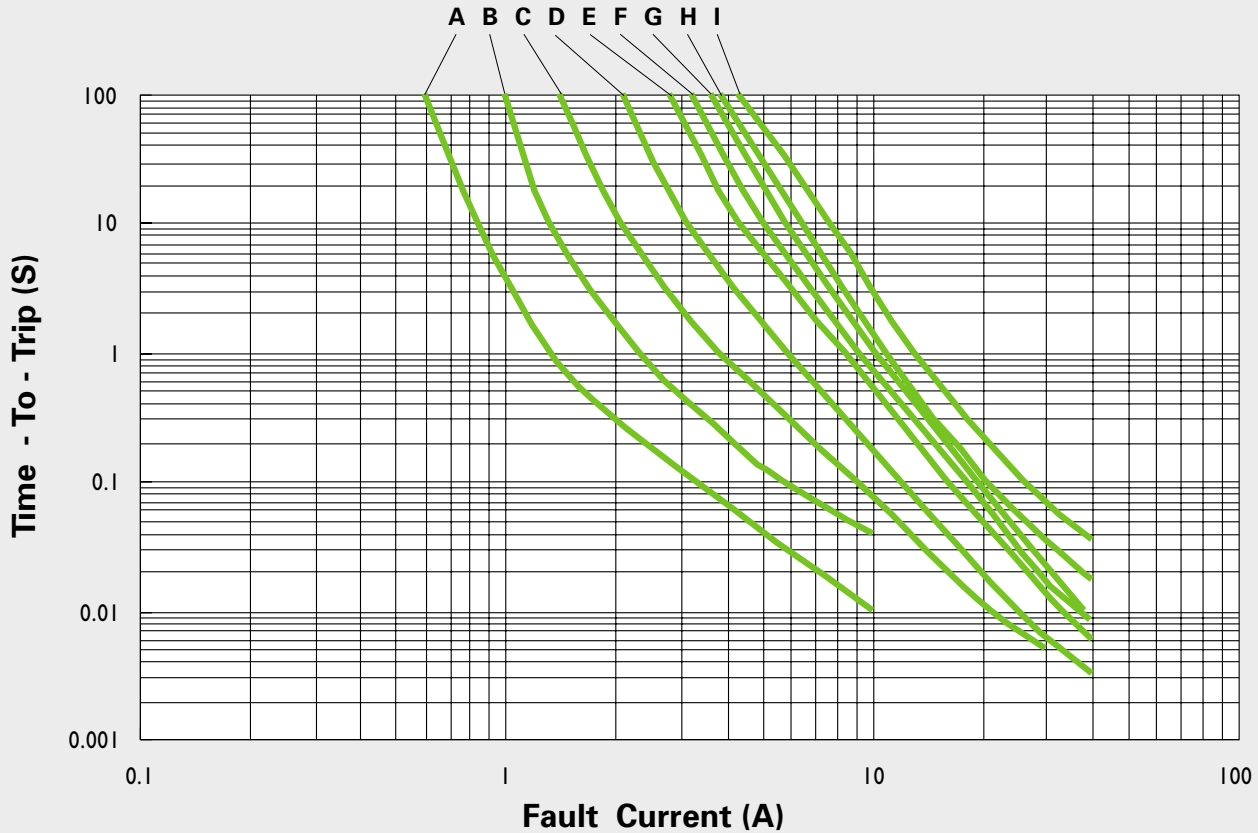
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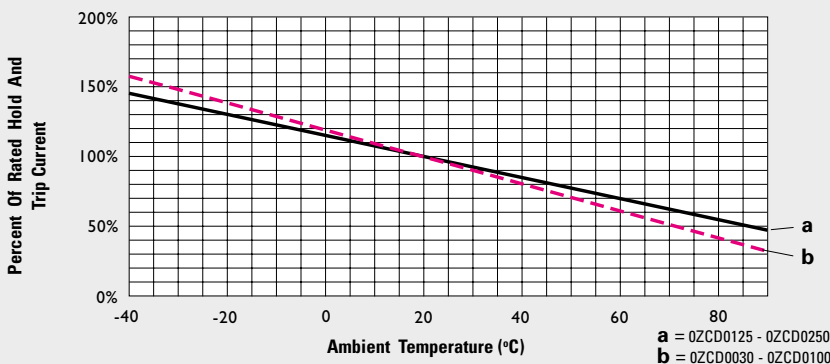
0ZCD1006C

Typical Time - To - Trip at 23°C

(See Elec. Characteristics Table for P/N - Curve Correlation)



Thermal Derating Curve



Cautionary Notes

1. Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.
2. These Polymer PTC (PPTC) devices are intended for protection against occasional overcurrent/ overtemperature fault conditions and may not be suitable for use in applications where repeated and/ or prolonged fault conditions are anticipated.
3. Avoid contact of PTC device with chemical solvent. Prolonged contact may adversely impact the PTC performance.
4. These PTC devices may not be suitable for use in circuits with a large inductance, as the PTC trip can generate circuit voltage spikes above the PTC rated voltage.

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